AMD Xilinx - XCV100E-6FG256I Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	600
Number of Logic Elements/Cells	2700
Total RAM Bits	81920
Number of I/O	176
Number of Gates	128236
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv100e-6fg256i

resources. The abundance of routing resources permits the Virtex-E family to accommodate even the largest and most complex designs.

Virtex-E FPGAs are SRAM-based, and are customized by loading configuration data into internal memory cells. Configuration data can be read from an external SPROM (master serial mode), or can be written into the FPGA (SelectMAP™, slave serial, and JTAG modes).

The standard Xilinx Foundation Series™ and Alliance Series™ Development systems deliver complete design support for Virtex-E, covering every aspect from behavioral and schematic entry, through simulation, automatic design translation and implementation, to the creation and downloading of a configuration bit stream.

Higher Performance

Virtex-E devices provide better performance than previous generations of FPGAs. Designs can achieve synchronous system clock rates up to 240 MHz including I/O or 622 Mb/s using Source Synchronous data transmission architectures. Virtex-E I/Os comply fully with 3.3 V PCI specifications, and interfaces can be implemented that operate at 33 MHz or 66 MHz.

While performance is design-dependent, many designs operate internally at speeds in excess of 133 MHz and can achieve over 311 MHz. Table 2 shows performance data for representative circuits, using worst-case timing parameters.

Table 2: **Performance for Common Circuit Functions**

Function	Bits	Virtex-E (-7)
Register-to-Register		
Adder	16 64	4.3 ns 6.3 ns
Pipelined Multiplier	8 x 8 16 x 16	4.4 ns 5.1 ns
Address Decoder	16 64	3.8 ns 5.5 ns
16:1 Multiplexer		4.6 ns
Parity Tree	9 18 36	3.5 ns 4.3 ns 5.9 ns
Chip-to-Chip		
HSTL Class IV		
LVTTL,16mA, fast slew		
LVDS		
LVPECL		

Virtex-E Device/Package Combinations and Maximum I/O

Table 3: **Virtex-E Family Maximum User I/O by Device/Package (Excluding Dedicated Clock Pins)**

	XCV 50E	XCV 100E	XCV 200E	XCV 300E	XCV 400E	XCV 600E	XCV 1000E	XCV 1600E	XCV 2000E	XCV 2600E	XCV 3200E
CS144	94	94	94								
PQ240	158	158	158	158	158						
HQ240						158	158				
BG352		196	260	260							
BG432				316	316	316					
BG560					404	404	404	404	404		
FG256	176	176	176	176							
FG456			284	312							
FG676					404	444					
FG680						512	512	512	512		
FG860							660	660	660		
FG900						512	660	700			
FG1156							660	724	804	804	804

Date	Version	Revision
11/20/00	1.8	• Upgraded speed grade -8 numbers in **Virtex-E Electrical Characteristics** tables to Preliminary. • Updated minimums in Table 13 and added notes to Table 14. • Added to note 2 to **Absolute Maximum Ratings**. • Changed speed grade -8 numbers for $T_{SHCKO32}$, T_{REG}, T_{BCCS}, and T_{ICKOF}. • Changed all minimum hold times to –0.4 under **Global Clock Setup and Hold for LVTTL Standard, with DLL**. • Revised maximum T_{DLLPW} in -6 speed grade for **DLL Timing Parameters**. • Changed GCLK0 to BA22 for FG860 package in Table 46.
2/12/01	1.9	• Revised footnote for Table 14. • Added numbers to **Virtex-E Electrical Characteristics** tables for XCV1000E and XCV2000E devices. • Updated Table 27 and Table 78 to include values for XCV400E and XCV600E devices. • Revised Table 62 to include pinout information for the XCV400E and XCV600E devices in the BG560 package. • Updated footnotes 1 and 2 for Table 76 to include XCV2600E and XCV3200E devices.
4/2/01	2.0	• Updated numerous values in **Virtex-E Switching Characteristics** tables. • Converted data sheet to modularized format. See the **Virtex-E Data Sheet** section.
10/25/01	2.1	• Updated the **Virtex-E Device/Package Combinations and Maximum I/O** table to show XCV3200E in the FG1156 package.
11/09/01	2.2	• Minor edits.
07/17/02	2.3	• Data sheet designation upgraded from Preliminary to Production.

Virtex-E Data Sheet

The Virtex-E Data Sheet contains the following modules:

- DS022-1, Virtex-E 1.8V FPGAs:
  Introduction and Ordering Information (Module 1)
- DS022-2, Virtex-E 1.8V FPGAs:
  Functional Description (Module 2)
- DS022-3, Virtex-E 1.8V FPGAs:
  DC and Switching Characteristics (Module 3)
- DS022-4, Virtex-E 1.8V FPGAs:
  Pinout Tables (Module 4)

For in-circuit debugging, an optional download and readback cable is available. This cable connects the FPGA in the target system to a PC or workstation. After downloading the design into the FPGA, the designer can single-step the logic, readback the contents of the flip-flops, and so observe the internal logic state. Simple modifications can be downloaded into the system in a matter of minutes.

Configuration

Virtex-E devices are configured by loading configuration data into the internal configuration memory. Note that attempting to load an incorrect bitstream causes configuration to fail and can damage the device.

Some of the pins used for configuration are dedicated pins, while others can be re-used as general purpose inputs and outputs once configuration is complete.

The following are dedicated pins:

- Mode pins (M2, M1, M0)
- Configuration clock pin (CCLK)
- $\overline{\text{PROGRAM}}$ pin
- DONE pin
- Boundary Scan pins (TDI, TDO, TMS, TCK)

Depending on the configuration mode chosen, CCLK can be an output generated by the FPGA, or can be generated externally and provided to the FPGA as an input. The $\overline{\text{PROGRAM}}$ pin must be pulled High prior to reconfiguration.

Note that some configuration pins can act as outputs. For correct operation, these pins require a V_{CCO} of 3.3 V or 2.5 V. At 3.3 V the pins operate as LVTTL, and at 2.5 V they operate as LVCMOS. All affected pins fall in banks 2 or 3. The configuration pins needed for SelectMap (CS, Write) are located in bank 1.

Configuration Modes

Virtex-E supports the following four configuration modes.

- Slave-serial mode
- Master-serial mode
- SelectMAP mode
- Boundary Scan mode (JTAG)

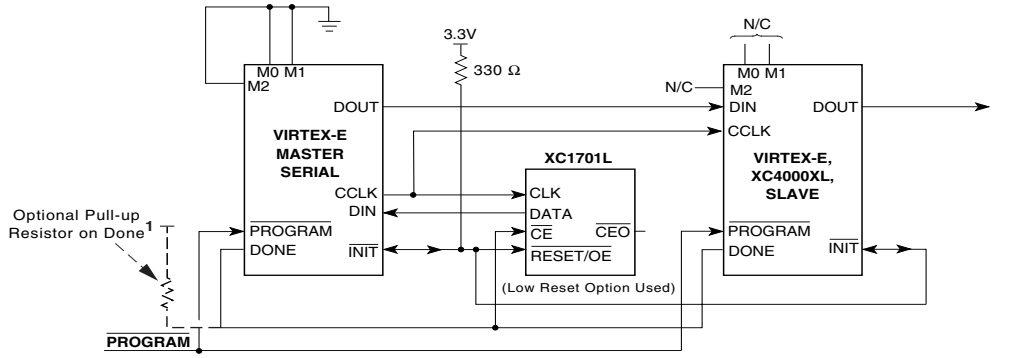
The Configuration mode pins (M2, M1, M0) select among these configuration modes with the option in each case of having the IOB pins either pulled up or left floating prior to configuration. The selection codes are listed in Table 8.

Configuration through the Boundary Scan port is always available, independent of the mode selection. Selecting the Boundary Scan mode simply turns off the other modes. The three mode pins have internal pull-up resistors, and default to a logic High if left unconnected. However, it is recommended to drive the configuration mode pins externally.

Table 8: **Configuration Codes**

Configuration Mode	M2[1]	M1	M0	CCLK Direction	Data Width	Serial D_{out}	Configuration Pull-ups[1]
Master-serial mode	0	0	0	Out	1	Yes	No
Boundary Scan mode	1	0	1	N/A	1	No	No
SelectMAP mode	1	1	0	In	8	No	No
Slave-serial mode	1	1	1	In	1	Yes	No
Master-serial mode	1	0	0	Out	1	Yes	Yes
Boundary Scan mode	0	0	1	N/A	1	No	Yes
SelectMAP mode	0	1	0	In	8	No	Yes
Slave-serial mode	0	1	1	In	1	Yes	Yes

Notes:
1. M2 is sampled continuously from power up until the end of the configuration. Toggling M2 while INIT is being held externally Low can cause the configuration pull-up settings to change.



Note 1: If none of the Virtex FPGAs have been selected to drive DONE, an external pull-up resistor of 330 Ω should be added to the common DONE line. (For Spartan-XL devices, add a 4.7K Ω pull-up resistor.) This pull-up is not needed if the DriveDONE attribute is set. If used, DriveDONE should be selected only for the last device in the configuration chain.

XCVE_ds_013_050103

Figure 13: **Master/Slave Serial Mode Circuit Diagram**

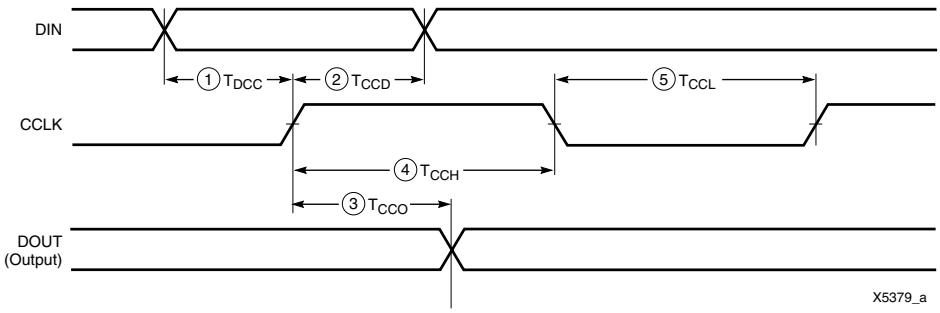


Figure 14: **Slave-Serial Mode Programming Switching Characteristics**

Master-Serial Mode

In master-serial mode, the CCLK output of the FPGA drives a Xilinx Serial PROM that feeds bit-serial data to the DIN input. The FPGA accepts this data on each rising CCLK edge. After the FPGA has been loaded, the data for the next device in a daisy-chain is presented on the DOUT pin after the rising CCLK edge. The maximum capacity for a single LOUT/DOUT write is 2^{20}-1 (1,048,575) 32-bit words, or 33,554,4000 bits.

The interface is identical to slave-serial except that an internal oscillator is used to generate the configuration clock (CCLK). A wide range of frequencies can be selected for CCLK, which always starts at a slow default frequency. Configuration bits then switch CCLK to a higher frequency for the remainder of the configuration. Switching to a lower frequency is prohibited.

The CCLK frequency is set using the ConfigRate option in the bitstream generation software. The maximum CCLK frequency that can be selected is 60 MHz. When selecting a CCLK frequency, ensure that the serial PROM and any daisy-chained FPGAs are fast enough to support the clock rate.

On power-up, the CCLK frequency is approximately 2.5 MHz. This frequency is used until the ConfigRate bits have been loaded when the frequency changes to the selected ConfigRate. Unless a different frequency is specified in the design, the default ConfigRate is 4 MHz.

In a full master/slave system (Figure 13), the left-most device operates in master-serial mode. The remaining devices operate in slave-serial mode. The SPROM $\overline{\text{RESET}}$ pin is driven by $\overline{\text{INIT}}$, and the $\overline{\text{CE}}$ input is driven by DONE. There is the potential for contention on the DONE pin, depending on the start-up sequence options chosen.

The sequence of operations necessary to configure a Virtex-E FPGA serially appears in Figure 15.

Termination Resistor Packs

Resistor packs are available with the values and the configuration required for LVDS and LVPECL termination from Bourns, Inc., as listed in Table. For pricing and availability, please contact Bourns directly at **http://www.bourns.com**.

Table 40: **Bourns LVDS/LVPECL Resistor Packs**

Part Number	I/O Standard	Term. for:	Pairs/ Pack	Pins
CAT16–LV2F6	LVDS	Driver	2	8
CAT16–LV4F12	LVDS	Driver	4	16
CAT16–PC2F6	LVPECL	Driver	2	8
CAT16–PC4F12	LVPECL	Driver	4	16
CAT16–PT2F2	LVDS/LVPECL	Receiver	2	8
CAT16–PT4F4	LVDS/LVPECL	Receiver	4	16

LVDS Design Guide

The SelectI/O library elements have been expanded for Virtex-E devices to include new LVDS variants. At this time all of the cells might not be included in the Synthesis libraries. The 2.1i-Service Pack 2 update for Alliance and Foundation software includes these cells in the VHDL and Verilog libraries. It is necessary to combine these cells to create the P-side (positive) and N-side (negative) as described in the input, output, 3-state and bidirectional sections.

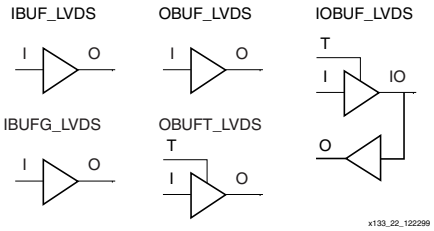


Figure 58: **LVDS elements**

Creating LVDS Global Clock Input Buffers

Global clock input buffers can be combined with adjacent IOBs to form LVDS clock input buffers. P-side is the GCLKPAD location; N-side is the adjacent IO_LVDS_DLL site.

Table 41: **Global Clock Input Buffer Pair Locations**

	GCLK 3		GCLK 2		GCLK 1		GCLK 0	
Pkg	P	N	P	N	P	N	P	N
CS144	A6	C6	A7	B7	M7	M6	K7	N8
PQ240	P213	P215	P210	P209	P89	P87	P92	P93
HQ240	P213	P215	P210	P209	P89	P87	P92	P93
BG352	D14	A15	B14	A13	AF14	AD14	AE13	AC13
BG432	D17	C17	A16	B16	AK16	AL17	AL16	AH15
BG560	A17	C18	D17	E17	AJ17	AM18	AL17	AM17
FG256	B8	A7	C9	A8	R8	T8	N8	N9
FG456	C11	B11	A11	D11	YII	AA11	W12	U12
FG676	E13	B13	C13	F14	AB13	AF13	AA14	AC14
FG680	A20	C22	D21	A19	AU22	AT22	AW19	AT21
FG860	C22	A22	B22	D22	AY22	AW21	BA22	AW20
FG900	C15	A15	E15	E16	AK16	AH16	AJ16	AF16
FG1156	E17	C17	D17	J18	AI19	AL17	AH18	AM18

HDL Instantiation

Only one global clock input buffer is required to be instantiated in the design and placed on the correct GCLKPAD location. The N-side of the buffer is reserved and no other IOB is allowed to be placed on this location.

In the physical device, a configuration option is enabled that routes the pad wire to the differential input buffer located in the GCLKIOB. The output of this buffer then drives the output of the GCLKIOB cell. In EPIC it appears that the second buffer is unused. Any attempt to use this location for another purpose leads to a DRC error in the software.

VHDL Instantiation

```
gclk0_p : IBUFG_LVDS port map
(I=>clk_external, O=>clk_internal);
```

Verilog Instantiation

```
IBUFG_LVDS gclk0_p (.I(clk_external),
.O(clk_internal));
```

Location constraints

All LVDS buffers must be explicitly placed on a device. For the global clock input buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET clk_external LOC = GCLKPAD3;
```

GCLKPAD3 can also be replaced with the package pin name such as D17 for the BG432 package.

The register elements can be packed in the IOB using the IOB property to TRUE on the register or by using the “map -pr [i|o|b]” where “i” is inputs only, “o” is outputs only and “b” is both inputs and outputs.

To improve design coding times VHDL and Verilog synthesis macro libraries have been developed to explicitly create these structures. The input library macros are listed below. The 3-state is configured to be 3-stated at GSR and when the PRE,CLR,S or R is asserted and shares it's clock enable with the output register. If this is not desirable then the library can be updated by the user for the desired functionality. The O and OB inputs to the macros are the external net connections.

Creating a LVDS Bidirectional Buffer

LVDS bidirectional buffers can be placed in a wide number of IOB locations. The exact locations are dependent on the package used. The Virtex-E package information lists the possible locations as IO_L#P for the P-side and IO_L#N for the N-side, where # is the pair number.

HDL Instantiation

Both bidirectional buffers are required to be instantiated in the design and placed on the correct IO_L#P and IO_L#N locations. The IOB must have the same net source the following pins, clock (C), set/reset (SR), 3-state (T), 3-state clock enable (TCE), output (O), output clock enable (OCE). In addition, the output (O) pins must be inverted with respect to each other, and if output registers are used, the INIT states must be opposite values (one HIGH and one LOW). If 3-state registers are used, they must be initialized to the same state. Failure to follow these rules leads to DRC errors in the software.

VHDL Instantiation

```
data0_p:   IOBUF_LVDS port map
(I=>data_out(0), T=>data_tri,
IO=>data_p(0), O=>data_int(0));

data0_inv: INV        port map
(I=>data_out(0),   O=>data_n_out(0));

data0_n  : IOBUF_LVDS port map
(I=>data_n_out(0), T=>data_tri,
IO=>data_n(0), O=>open);
```

Verilog Instantiation

```
IOBUF_LVDS data0_p(.I(data_out[0]),
.T(data_tri), .IO(data_p[0]),
.O(data_int[0]);

INV        data0_inv (.I(data_out[0],
.O(data_n_out[0]);

IOBUF_LVDS
data0_n(.I(data_n_out[0]),.T(data_tri),.
IO(data_n[0]).O());
```

Location Constraints

All LVDS buffers must be explicitly placed on a device. For the output buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET data_p<0> LOC = D28; # IO_L0P

NET data_n<0> LOC = B29; # IO_L0N
```

Synchronous vs. Asynchronous Bidirectional Buffers

If the output side of the bidirectional buffers are synchronous (registered in the IOB), then any IO_L#PIN pair can be used. If the output side of the bidirectional buffers are asynchronous (no output register), then they must use one of the pairs that is a part of the asynchronous LVDS IOB group. This applies for either the 3-state pin or the data out pin.

The LVDS pairs that can be used as asynchronous bidirectional buffers are listed in the Virtex-E pinout tables. Some pairs are marked as asynchronous capable for all devices in that package, and others are marked as available only for that device in the package. If the device size might change at some point in the product’s lifetime, then only the common pairs for all packages should be used.

Adding Output and 3-State Registers

All LVDS buffers can have an output and input registers in the IOB. The output registers must be in both the P-side and N-side IOBs, the input register is only in the P-side. All the normal IOB register options are available (FD, FDE, FDC, FDCE, FDP, FDPE, FDR, FDRE, FDS, FDSE, LD, LDE, LDC, LDCE, LDP, LDPE). The register elements can be inferred or explicitly instantiated in the HDL code. Special care must be taken to insure that the D pins of the registers are inverted and that the INIT states of the registers are opposite. The 3-state (T), 3-state clock enable (CE), clock pin (C), output clock enable (CE), and set/reset (CLR/PRE or S/R) pins must connect to the same source. Failure to do this leads to a DRC error in the software.

The register elements can be packed in the IOB using the IOB property to TRUE on the register or by using the “map -pr [i|o|b]” where “i” is inputs only, “o” is outputs only and “b” is both inputs and outputs. To improve design coding times VHDL and Verilog synthesis macro libraries have been developed to explicitly create these structures. The bidirectional I/O library macros are listed in Table 44. The 3-state is configured to be 3-stated at GSR and when the PRE,CLR,S or R is asserted and shares its clock enable with the output and input register. If this is not desirable then the library can be updated be the user for the desired functionality. The I/O and IOB inputs to the macros are the external net connections.

Table 2: **IOB Input Switching Characteristics *(Continued)***

Description[2]	Symbol	Device	Speed Grade[1] Min	-8	-7	-6	Units
Sequential Delays							
Clock CLK							
Minimum Pulse Width, High	T_{CH}	All	0.56	1.2	1.3	1.4	ns, min
Minimum Pulse Width, Low	T_{CL}		0.56	1.2	1.3	1.4	ns, min
Clock CLK to output IQ	T_{IOCKIQ}		0.18	0.4	0.7	0.7	ns, max
Setup and Hold Times with respect to Clock at IOB Input Register							
Pad, no delay	T_{IOPICK}/ T_{IOICKP}	All	0.69 / 0	1.3 / 0	1.4 / 0	1.5 / 0	ns, min
Pad, with delay	$T_{IOPICKD}$/ $T_{IOICKPD}$	XCV50E	1.25 / 0	2.8 / 0	2.9 / 0	2.9 / 0	ns, min
		XCV100E	1.25 / 0	2.8 / 0	2.9 / 0	2.9 / 0	ns, min
		XCV200E	1.33 / 0	3.0 / 0	3.1 / 0	3.1 / 0	ns, min
		XCV300E	1.33 / 0	3.0 / 0	3.1 / 0	3.1 / 0	ns, min
		XCV400E	1.37 / 0	3.1 / 0	3.2 / 0	3.2 / 0	ns, min
		XCV600E	1.49 / 0	3.4 / 0	3.5 / 0	3.5 / 0	ns, min
		XCV1000E	1.49 / 0	3.4 / 0	3.5 / 0	3.5 / 0	ns, min
		XCV1600E	1.53 / 0	3.5 / 0	3.6 / 0	3.6 / 0	ns, min
		XCV2000E	1.53 / 0	3.5 / 0	3.6 / 0	3.6 / 0	ns, min
		XCV2600E	1.53 / 0	3.5 / 0	3.6 / 0	3.6 / 0	ns, min
		XCV3200E	1.53 / 0	3.5 / 0	3.6 / 0	3.6 / 0	ns, min
ICE input	$T_{IOICECK}$/ $T_{IOCKICE}$	All	0.28 / 0.0	0.55 / 0.01	0.7 / 0.01	0.7 / 0.01	ns, min
SR input (IFF, synchronous)	$T_{IOSRCKI}$	All	0.38	0.8	0.9	1.0	ns, min
Set/Reset Delays							
SR input to IQ (asynchronous)	T_{IOSRIQ}	All	0.54	1.1	1.2	1.4	ns, max
GSR to output IQ	T_{GSRQ}	All	3.88	7.6	8.5	9.7	ns, max

Notes:
1. A Zero “0” Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed “best-case”, but if a “0” is listed, there is no positive hold time.
2. Input timing i for LVTTL is measured at 1.4 V. For other I/O standards, see Table 4.

Global Clock Input to Output Delay for LVTTL, 12 mA, Fast Slew Rate, *without* DLL

Description[1]	Symbol	Device	Speed Grade[2]				Units
			Min	-8	-7	-6	
LVTTL Global Clock Input to Output Delay using Output Flip-flop, 12 mA, Fast Slew Rate, *without* DLL. For data *output* with different standards, adjust the delays with the values shown in **IOB Output Switching Characteristics Standard Adjustments**, page 10.	T_{ICKOF}	XCV50E	1.5	4.2	4.4	4.6	ns
		XCV100E	1.5	4.2	4.4	4.6	ns
		XCV200E	1.5	4.3	4.5	4.7	ns
		XCV300E	1.5	4.3	4.5	4.7	ns
		XCV400E	1.5	4.4	4.6	4.8	ns
		XCV600E	1.6	4.5	4.7	4.9	ns
		XCV1000E	1.7	4.6	4.8	5.0	ns
		XCV1600E	1.8	4.7	4.9	5.1	ns
		XCV2000E	1.8	4.8	5.0	5.2	ns
		XCV2600E	2.0	5.0	5.2	5.4	ns
		XCV3200E	2.2	5.2	5.4	5.6	ns

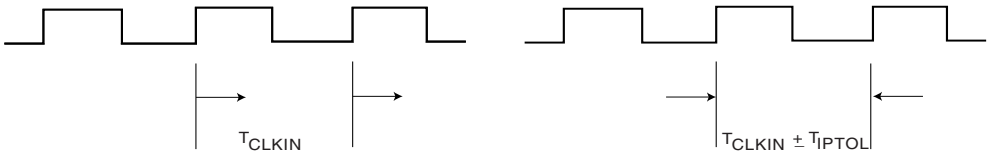
Notes:
1. Listed above are representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible IOB and CLB flip-flops are clocked by the global clock net.
2. Output timing is measured at 50% V_{CC} threshold with 35 pF external capacitive load. For other I/O standards and different loads, see Table 3 and Table 4.

DLL Timing Parameters

All devices are 100 percent functionally tested. Because of the difficulty in directly measuring many internal timing parameters, those parameters are derived from benchmark timing patterns. The following guidelines reflect worst-case values across the recommended operating conditions.

Description	Symbol	F_{CLKIN}	Speed Grade						Units
			-8		-7		-6		
			Min	Max	Min	Max	Min	Max	
Input Clock Frequency (CLKDLLHF)	FCLKINHF		60	350	60	320	60	275	MHz
Input Clock Frequency (CLKDLL)	FCLKINLF		25	160	25	160	25	135	MHz
Input Clock Low/High Pulse Width	T_{DLLPW}	≥2□5 MHz	5.0		5.0		5.0		ns
		≥□50 MHz	3.0		3.0		3.0		ns
		≥100 MHz	2.4		2.4		2.4		ns
		≥□150 MHz	2.0		2.0		2.0		ns
		≥□200 MHz	1.8		1.8		1.8		ns
		≥□250 MHz	1.5		1.5		1.5		ns
		≥□300 MHz	1.3		1.3		NA		ns

Period Tolerance: the allowed input clock period change in nanoseconds.



Output Jitter: the difference between an ideal reference clock edge and the actual design.

Phase Offset and Maximum Phase Difference

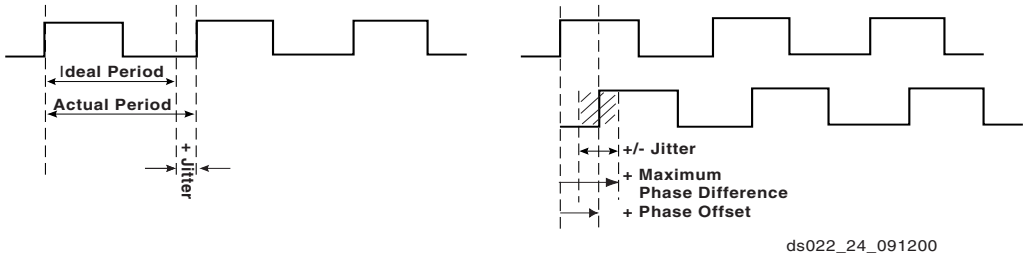


Figure 4: **DLL Timing Waveforms**

Table 6: **PQ240 — XCV50E, XCV100E, XCV200E, XCV300E, XCV400E**

Pin #	Pin Description	Bank
P173	IO_L16N_Y	2
P171	IO_VREF_L17P_Y	2
P170	IO_L17N_Y	2
P169	IO	2
P168[1]	IO_VREF_L18P_Y	2
P167	IO_D1_L18N_Y	2
P163	IO_D2_L19P_YY	2
P162	IO_L19N_YY	2
P161	IO	2
P160	IO_L20P_Y	2
P159	IO_L20N_Y	2
P157	IO_VREF_L21P_Y	2
P156	IO_D3_L21N_Y	2
P155	IO_L22P_Y	2
P154[3]	IO_VREF_L22N_Y	2
P153	IO_L23P_YY	2
P152	IO_L23N_YY	2
P149	IO	3
P147[3]	IO_VREF	3
P145	IO_D4_L24P_Y	3
P144	IO_VREF_L24N_Y	3
P142	IO_L25P_Y	3
P141	IO_L25N_Y	3
P140	IO	3
P139	IO_L26P_YY	3
P138	IO_D5_L26N_YY	3
P134	IO_D6_L27P_Y	3
P133[1]	IO_VREF_L27N_Y	3
P132	IO	3
P131	IO_L28P_Y	3
P130	IO_VREF_L28N_Y	3
P128	IO_L29P_Y	3
P127	IO_L29N_Y	3
P126[2]	IO_VREF_L30P_Y	3

Table 6: **PQ240 — XCV50E, XCV100E, XCV200E, XCV300E, XCV400E**

Pin #	Pin Description	Bank
P125	IO_L30N_Y	3
P124	IO_D7_L31P_YY	3
P123	IO_INIT_L31N_YY	3
P118	IO_L32P_YY	4
P117	IO_L32N_YY	4
P115[2]	IO_VREF	4
P114	IO_L33P_YY	4
P113	IO_L33N_YY	4
P111	IO_VREF_L34P_YY	4
P110	IO_L34N_YY	4
P109	IO	4
P108[1]	IO_VREF_L35P_YY	4
P107	IO_L35N_YY	4
P103	IO_L36P_YY	4
P102	IO_L36N_YY	4
P101	IO	4
P100	IO_L37P_Y	4
P99	IO_L37N_Y	4
P97	IO_VREF_L38P_Y	4
P96	IO_L38N_Y	4
P95	IO_L39P_Y	4
P94[3]	IO_VREF_L39N_Y	4
P93	IO_LVDS_DLL_L40P	4
P92	GCK0	4
P89	GCK1	5
P87	IO_LVDS_DLL_L40N	5
P86[3]	IO_VREF	5
P84	IO_VREF_L41P_Y	5
P82	IO_L41N_Y	5
P81	IO	5
P80	IO	5
P79	IO_L42P_YY	5
P78	IO_L42N_YY	5

Table 7: **PQ240 Differential Pin Pair Summary XCV50E, XCV100E, XCV200E, XCV300E, XCV400E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
48	6	P56	P57	√	-
49	6	P52	P53	2	-
50	6	P49	P50	3	VREF
51	6	P46	P47	4	VREF
52	6	P41	P42	√	-
53	6	P38	P39	2	-
54	6	P35	P36	4	VREF
55	6	P33	P34	5	VREF
56	7	P27	P28	√	-
57	7	P23	P24	4	VREF
58	7	P20	P21	2	-
59	7	P17	P18	√	-
60	7	P12	P13	4	VREF
61	7	P9	P10	3	VREF
62	7	P6	P7	2	-
63	7	P4	P5	6	VREF

Notes:
1. AO in the XCV50E.
2. AO in the XCV50E, 100E, 200E, 300E.
3. AO in the XCV50E, 200E, 300E, 400E.
4. AO in the XCV50E, 300E, 400E.
5. AO in the XCV100E, 200E, 400E.
6. AO in the XCV100E, 400E.
7. AO in the XCV50E, 200E, 400E.
8. AO in the XCV100E.

HQ240 High-Heat Quad Flat-Pack Packages

XCV600E and XCV1000E devices in High-heat dissipation Quad Flat-pack packages have footprint compatibility. Pins labeled I0_VREF can be used as either in all parts unless device-dependent as indicated in the footnotes. If the pin is not used as V_{REF}, it can be used as general I/O. Immediately following Table 8, see Table 9 for Differential Pair information.

Table 8: **HQ240 — XCV600E, XCV1000E**

Pin #	Pin Description	Bank
P240	VCCO	7
P239	TCK	NA
P238	IO	0
P237	IO_L0N	0
P236	IO_VREF_L0P	0
P235	IO_L1N_YY	0
P234	IO_L1P_YY	0
P233	GND	NA
P232	VCCO	0
P231	IO_VREF	0
P230	IO_VREF	0
P229	IO_VREF_L2N_YY	0
P228	IO_L2P_YY	0
P227	GND	NA
P226	VCCO	0
P225	VCCINT	NA
P224	IO_L3N_YY	0
P223	IO_L3P_YY	0
P222	IO_VREF	0[1]
P221	IO_L4N_Y	0
P220	IO_L4P_Y	0
P219	GND	NA
P218	IO_VREF_L5N_Y	0
P217	IO_L5P_Y	0
P216	IO_VREF	0
P215	IO_LVDS_DLL_L6N	0
P214	VCCINT	NA
P213	GCK3	0
P212	VCCO	0
P211	GND	NA

Table 12: **BG432 — XCV300E, XCV400E, XCV600E**

Bank	Pin Description	Pin #
4	IO_L70N_Y	AK4
4	IO_L71P_YY	AJ5
4	IO_L71N_YY	AH6
4	IO_VREF_L72P_YY	AL4
4	IO_L72N_YY	AK5
4	IO_L73P_Y	AJ6
4	IO_L73N_Y	AH7
4	IO_L74P_YY	AL5
4	IO_L74N_YY	AK6
4	IO_VREF_L75P_YY	AJ7
4	IO_L75N_YY	AL6
4	IO_L76P_Y	AH9
4	IO_L76N_Y	AJ8
4	IO_VREF_L77P_Y	AK8[1]
4	IO_L77N_Y	AJ9
4	IO_VREF_L78P_YY	AL8
4	IO_L78N_YY	AK9
4	IO_L79P_YY	AK10
4	IO_L79N_YY	AL10
4	IO_L80P_YY	AH12
4	IO_L80N_YY	AK11
4	IO_L81P_YY	AJ12
4	IO_L81N_YY	AK12
4	IO_L82P_YY	AH13
4	IO_L82N_YY	AJ13
4	IO_VREF_L83P_YY	AL13
4	IO_L83N_YY	AK14
4	IO_L84P_Y	AH14
4	IO_L84N_Y	AJ14
4	IO_VREF_L85P_Y	AK15[2]
4	IO_L85N_Y	AJ15
4	IO_LVDS_DLL_L86P	AH15
5	GCK1	AK16
5	IO	AH20
5	IO	AJ19

Table 12: **BG432 — XCV300E, XCV400E, XCV600E**

Bank	Pin Description	Pin #
5	IO	AJ23
5	IO	AJ24
5	IO_LVDS_DLL_L86N	AL17
5	IO_L87P_Y	AK17
5	IO_VREF_L87N_Y	AJ17[2]
5	IO_L88P_Y	AH17
5	IO_L88N_Y	AK18
5	IO_L89P_YY	AL19
5	IO_VREF_L89N_YY	AJ18
5	IO_L90P_YY	AH18
5	IO_L90N_YY	AL20
5	IO_L91P_YY	AK20
5	IO_L91N_YY	AH19
5	IO_L92P_YY	AJ20
5	IO_L92N_YY	AK21
5	IO_L93P_YY	AJ21
5	IO_L93N_YY	AL22
5	IO_L94P_YY	AJ22
5	IO_VREF_L94N_YY	AK23
5	IO_L95P_Y	AH22
5	IO_VREF_L95N_Y	AL24[1]
5	IO_L96P_Y	AK24
5	IO_L96N_Y	AH23
5	IO_L97P_YY	AK25
5	IO_VREF_L97N_YY	AJ25
5	IO_L98P_YY	AL26
5	IO_L98N_YY	AK26
5	IO_L99P_Y	AH25
5	IO_L99N_Y	AL27
5	IO_L100P_YY	AJ26
5	IO_VREF_L100N_YY	AK27
5	IO_L101P_YY	AH26
5	IO_L101N_YY	AL28
5	IO_L102P_Y	AJ27
5	IO_L102N_Y	AK28

Table 12: **BG432 — XCV300E, XCV400E, XCV600E**

Bank	Pin Description	Pin #
6	IO	AA30
6	IO	AC30
6	IO	AD29
6	IO	U31
6	IO	W28
6	IO_L103N_YY	AJ30
6	IO_L103P_YY	AH30
6	IO_L104N	AG28
6	IO_L104P	AH31
6	IO_L105N_Y	AG29
6	IO_L105P_Y	AG30
6	IO_VREF_L106N_Y	AF28
6	IO_L106P_Y	AG31
6	IO_L107N	AF29
6	IO_L107P	AF30
6	IO_L108N_Y	AE28
6	IO_L108P_Y	AF31
6	IO_VREF_L109N_YY	AE30
6	IO_L109P_YY	AD28
6	IO_L110N_Y	AD30
6	IO_L110P_Y	AD31
6	IO_VREF_L111N_Y	AC28[1]
6	IO_L111P_Y	AC29
6	IO_VREF_L112N_YY	AB28
6	IO_L112P_YY	AB29
6	IO_L113N_YY	AB31
6	IO_L113P_YY	AA29
6	IO_L114N_Y	Y28
6	IO_L114P_Y	Y29
6	IO_L115N_Y	Y30
6	IO_L115P_Y	Y31
6	IO_L116N_Y	W29
6	IO_L116P_Y	W30
6	IO_VREF_L117N_YY	V28
6	IO_L117P_YY	V29
6	IO_L118N_Y	V30

Table 12: **BG432 — XCV300E, XCV400E, XCV600E**

Bank	Pin Description	Pin #
6	IO_L118P_Y	U29
6	IO_VREF_L119N_Y	U28[2]
6	IO_L119P_Y	U30
6	IO	T30
7	IO	C30
7	IO	H29
7	IO	H31
7	IO	L29
7	IO	M31
7	IO	R28
7	IO_L120N_YY	T31
7	IO_L120P_YY	R29
7	IO_L121N_Y	R30
7	IO_VREF_L121P_Y	R31[2]
7	IO_L122N_Y	P29
7	IO_L122P_Y	P28
7	IO_L123N_YY	P30
7	IO_VREF_L123P_YY	N30
7	IO_L124N_Y	N28
7	IO_L124P_Y	N31
7	IO_L125N_Y	M29
7	IO_L125P_Y	M28
7	IO_L126N_Y	M30
7	IO_L126P_Y	L30
7	IO_L127N_YY	K31
7	IO_L127P_YY	K30
7	IO_L128N_YY	K28
7	IO_VREF_L128P_YY	J30
7	IO_L129N_Y	J29
7	IO_VREF_L129P_Y	J28[1]
7	IO_L130N_Y	H30
7	IO_L130P_Y	G30
7	IO_L131N_YY	H28
7	IO_VREF_L131P_YY	F31
7	IO_L132N_Y	G29

Table 18: **FG456 — XCV200E and XCV300E**

Bank	Pin Description	Pin #
3	IO_L50N_YY	P19
3	IO_L51P_YY	P18
3	IO_D5_L51N_YY	R21
3	IO_D6_L52P_Y	T22
3	IO_VREF_L52N_Y	R19
3	IO_L53P_Y	U22
3	IO_L53N_Y	R18
3	IO_L54P_YY	T21
3	IO_L54N_YY	V22
3	IO_L55P_YY	T20
3	IO_VREF_L55N_YY	U21
3	IO_L56P_YY	W22
3	IO_L56N_YY	T18
3	IO_L57P_YY	U19
3	IO_VREF_L57N_YY	U20
3	IO_L58P_YY	W21
3	IO_L58N_YY	AA22
3	IO_D7_L59P_YY	Y21
3	IO_INIT_L59N_YY	V19
3	IO	M22
4	GCK0	W12
4	IO	W14
4	IO	Y13
4	IO	Y17
4	IO	AA16[1]
4	IO	AA19
4	IO	AB12[1]
4	IO	AB17
4	IO	AB21[1]
4	IO_L60P_YY	W18
4	IO_L60N_YY	AA20
4	IO_L61P	Y18
4	IO_L61N	V17
4	IO_VREF_L62P_YY	AB20
4	IO_L62N_YY	W17
4	IO_L63P	AA18

Table 18: **FG456 — XCV200E and XCV300E**

Bank	Pin Description	Pin #
4	IO_L63N	V16
4	IO_VREF_L64P_YY	AB19
4	IO_L64N_YY	AB18
4	IO_L65P_Y	W16
4	IO_L65N_Y	AA17
4	IO_L66P_Y	Y16
4	IO_L66N_Y	V15
4	IO_VREF_L67P_YY	AB16
4	IO_L67N_YY	Y15
4	IO_L68P_YY	AA15
4	IO_L68N_YY	AB15
4	IO_L69P_Y	W15
4	IO_L69N_Y	Y14
4	IO_L70P_Y	V14
4	IO_L70N_Y	AA14
4	IO_L71P	AB14
4	IO_L71N	V13
4	IO_VREF_L72P_YY	AA13
4	IO_L72N_YY	AB13
4	IO_L73P_Y	W13
4	IO_L73N_Y	AA12
4	IO_L74P_Y	Y12
4	IO_L74N_Y	V12
4	IO_LVDS_DLL_L75P	U12
5	IO	U11[1]
5	IO	V8
5	IO	W5
5	IO	AA3[1]
5	IO	AA9
5	IO	AA10
5	IO	AB4
5	IO	AB7[1]
5	IO	AB8
5	GCK1	Y11
5	IO_LVDS_DLL_L75N	AA11
5	IO_L76P_Y	AB11

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
1	IO_L40P_YY	D20
1	IO_L41N_YY	F19
1	IO_VREF_L41P_YY	C21
1	IO_L42N_YY	B22
1	IO_L42P_YY	E20
1	IO_L43N_Y	A23
1	IO_L43P_Y	D21
1	IO_WRITE_L44N_YY	C22
1	IO_CS_L44P_YY	E21
2	IO	D25[1]
2	IO	D26
2	IO	E26
2	IO	F26
2	IO	H26[1]
2	IO	K26[1]
2	IO	M25[1]
2	IO	N26[1]
2	IO_D1	K24
2	IO_DOUT_BUSY_L45P_YY	E23
2	IO_DIN_D0_L45N_YY	F22
2	IO_L46P_YY	E24
2	IO_L46N_YY	F20
2	IO_L47P_Y	G21
2	IO_L47N_Y	G22
2	IO_VREF_L48P_Y	F24
2	IO_L48N_Y	H20
2	IO_L49P_Y	E25
2	IO_L49N_Y	H21
2	IO_L50P_YY	F23
2	IO_L50N_YY	G23
2	IO_VREF_L51P_YY	H23
2	IO_L51N_YY	J20
2	IO_L52P_YY	G24
2	IO_L52N_YY	H22
2	IO_L53P_Y	J21
2	IO_L53N_Y	G25

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
2	IO_VREF_L54P_Y	G26[2]
2	IO_L54N_Y	J22
2	IO_L55P_YY	H24
2	IO_L55N_YY	J23
2	IO_L56P_YY	J24
2	IO_VREF_L56N_YY	K20
2	IO_D2_L57P_YY	K22
2	IO_L57N_YY	K21
2	IO_L58P_YY	H25
2	IO_L58N_YY	K23
2	IO_L59P_Y	L20
2	IO_L59N_Y	J26
2	IO_L60P_Y	K25
2	IO_L60N_Y	L22
2	IO_L61P_Y	L21
2	IO_L61N_Y	L23
2	IO_L62P_Y	M20
2	IO_L62N_Y	L24
2	IO_VREF_L63P_YY	M23
2	IO_D3_L63N_YY	M22
2	IO_L64P_YY	L26
2	IO_L64N_YY	M21
2	IO_L65P_Y	N19
2	IO_L65N_Y	M24
2	IO_VREF_L66P_Y	M26
2	IO_L66N_Y	N20
2	IO_L67P_YY	N24
2	IO_L67N_YY	N21
2	IO_L68P_YY	N23
2	IO_L68N_YY	N22
3	IO	P24
3	IO	P26[1]
3	IO	R26[1]
3	IO	T26[1]
3	IO	U26[1]
3	IO	W25

FG676 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A √ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package. Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair are in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs than can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 21: **FG676 Differential Pin Pair Summary XCV400E, XCV600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
3	0	E13	B13	NA	IO_DLL_L21N
2	1	C13	F14	NA	IO_DLL_L21P
1	5	AB13	AF13	NA	IO_DLL_L115N
0	4	AA14	AC14	NA	IO_DLL_L115P
IOLVDS Total Pairs: 183, Asynchronous Output Pairs: 97					
0	0	F7	C4	1	-
1	0	C5	G8	√	-
2	0	E7	D6	√	VREF
3	0	F8	A4	NA	-
4	0	D7	B5	NA	-
5	0	G9	E8	√	VREF
6	0	F9	A5	√	-
7	0	C7	D8	1	-
8	0	E9	B7	1	VREF
9	0	D9	A7	NA	-
10	0	G10	B8	NA	VREF
11	0	F10	C9	√	-
12	0	E10	A8	1	-
13	0	D10	G11	√	-
14	0	F11	B10	√	-
15	0	E11	C10	NA	-
16	0	D11	G12	√	-
17	0	F12	C11	√	VREF

Table 21: **FG676 Differential Pin Pair Summary XCV400E, XCV600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
18	0	E12	A11	√	-
19	0	C12	D12	1	-
20	0	H13	A12	1	VREF
21	1	F14	B13	NA	IO_LVDS_DLL
22	1	F13	E14	NA	-
23	1	A14	D14	1	VREF
24	1	H14	C14	1	-
25	1	C15	G14	√	-
26	1	D15	E15	√	VREF
27	1	F15	C16	√	-
28	1	D16	G15	-	-
29	1	A17	E16	√	-
30	1	E17	C17	√	-
31	1	D17	F16	1	-
32	1	C18	F17	√	-
33	1	G16	A18	√	VREF
34	1	G17	C19	√	-
35	1	B19	D18	1	VREF
36	1	E18	D19	1	-
37	1	B20	F18	√	-
38	1	C20	G19	√	VREF
39	1	E19	G18	√	-
40	1	D20	A21	√	-
41	1	C21	F19	√	VREF
42	1	E20	B22	√	-
43	1	D21	A23	2	-
44	1	E21	C22	√	CS
45	2	E23	F22	√	DIN, D0
46	2	E24	F20	√	-
47	2	G21	G22	2	-
48	2	F24	H20	1	VREF
49	2	E25	H21	1	-
50	2	F23	G23	√	-
51	2	H23	J20	√	VREF

Table 22: **FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
5	IO_L166P_YY	AV26
5	IO_L166N_YY	AW27
5	IO_L167P_Y	AU26
5	IO_L167N_Y	AV27
5	IO_L168P_Y	AT26
5	IO_L168N_Y	AW28
5	IO_L169P_YY	AU27
5	IO_L169N_YY	AV28
5	IO_L170P_YY	AW29
5	IO_VREF_L170N_YY	AT27
5	IO_L171P_Y	AW30
5	IO_L171N_Y	AU28
5	IO_L172P_Y	AV30
5	IO_L172N_Y	AV29
5	IO_L173P_YY	AW31
5	IO_VREF_L173N_YY	AU29
5	IO_L174P_YY	AV31
5	IO_L174N_YY	AT29
5	IO_L175P_Y	AW32
5	IO_VREF_L175N_Y	AU30[3]
5	IO_L176P_Y	AW33
5	IO_L176N_Y	AT30
5	IO_L177P_YY	AV33
5	IO_VREF_L177N_YY	AU31
5	IO_L178P_YY	AT31
5	IO_L178N_YY	AW34
5	IO_L179P_Y	AV32
5	IO_L179N_Y	AV34
5	IO_L180P_Y	AU32
5	IO_L180N_Y	AW35
5	IO_L181P_YY	AT32
5	IO_VREF_L181N_YY	AV35
5	IO_L182P_YY	AU33
5	IO_L182N_YY	AW36
5	IO_L183P_Y	AT33
5	IO_VREF_L183N_Y	AV36[1]

Table 22: **FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
5	IO_L184P_Y	AU34
5	IO_L184N_Y	AU36
6	IO	W39
6	IO	AR37
6	IO	AR39
6	IO_L185N_YY	AR36
6	IO_L185P_YY	AT38
6	IO_L186N_Y	AR38
6	IO_L186P_Y	AP36
6	IO_VREF_L187N	AT39[1]
6	IO_L187P	AP37
6	IO_L188N	AP38
6	IO_L188P	AP39
6	IO_VREF_L189N_Y	AN36
6	IO_L189P_Y	AN38
6	IO_L190N_YY	AN37
6	IO_L190P_YY	AN39
6	IO_L191N	AM36
6	IO_L191P	AM38
6	IO_L192N_Y	AM37
6	IO_L192P_Y	AL36
6	IO_VREF_L193N_YY	AM39
6	IO_L193P_YY	AL37
6	IO_L194N_YY	AL38
6	IO_L194P_YY	AK36
6	IO_VREF_L195N	AL39[3]
6	IO_L195P	AK37
6	IO_L196N	AK38
6	IO_L196P	AJ36
6	IO_VREF_L197N_YY	AK39
6	IO_L197P_YY	AJ37
6	IO_L198N_YY	AJ38
6	IO_L198P_YY	AH37
6	IO_L199N	AJ39
6	IO_L199P	AH38

Table 25: **FG860 Differential Pin Pair Summary**
XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
52	1	D11	B15	√	VREF
53	1	C14	E11	2	-
54	1	B14	C10	2	-
55	1	E10	A13	√	VREF
56	1	C9	C13	√	-
57	1	A12	D9	1	VREF
58	1	C12	E9	1	-
59	1	D8	B12	√	VREF
60	1	E8	A11	√	-
61	1	A10	C7	5	-
62	1	B10	C6	5	-
63	1	B9	A9	√	VREF
64	1	E7	A8	√	-
65	1	C5	B8	5	-
66	1	A6	A7	1	VREF
67	1	D6	B7	1	-
68	1	C4	A5	2	-
69	1	E6	B6	√	CS
70	2	F5	D2	√	DIN, D0
71	2	E4	E2	3	-
72	2	D3	F2	1	-
73	2	E1	F4	2	VREF
74	2	G2	E3	4	-
75	2	F1	G5	2	-
76	2	G1	F3	1	VREF
77	2	G4	H1	√	-
78	2	J2	G3	2	-
79	2	H5	K2	1	-
80	2	H4	K1	√	VREF
81	2	L2	L3	√	-
82	2	L1	J5	5	VREF
83	2	J4	M3	2	-
84	2	J3	M1	√	VREF
85	2	N2	K4	√	-

Table 25: **FG860 Differential Pin Pair Summary**
XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
86	2	N3	K3	2	-
87	2	L5	P2	√	D1
88	2	P3	L4	√	D2
89	2	P1	R2	3	-
90	2	M5	R3	1	-
91	2	M4	R1	2	-
92	2	N4	T2	4	-
93	2	P5	T3	2	-
94	2	P4	T1	1	VREF
95	2	U2	R4	√	-
96	2	U3	T5	2	-
97	2	T4	V2	1	-
98	2	U5	V3	√	D3
99	2	V1	V5	√	-
100	2	W2	V4	5	-
101	2	W5	W1	2	-
102	2	Y2	W4	√	VREF
103	2	Y1	Y5	√	-
104	2	AA1	Y4	2	VREF
105	2	AA4	AA2	√	-
106	3	AB3	AC4	2	VREF
107	3	AB1	AC5	√	-
108	3	AD4	AC3	√	VREF
109	3	AC1	AD5	2	-
110	3	AE4	AD3	5	-
111	3	AE5	AD2	√	-
112	3	AE1	AF5	√	VREF
113	3	AE2	AG4	1	-
114	3	AG5	AF1	2	-
115	3	AH4	AF2	√	-
116	3	AF3	AJ4	1	VREF
117	3	AG1	AJ5	2	-
118	3	AG2	AK4	4	-
119	3	AG3	AL4	2	-

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
4	IO_L178N_YY	AL28
4	IO_L179P_YY	AE24[4]
4	IO_L179N_YY	AN28[5]
4	IO_L180P_Y	AJ27
4	IO_L180N_Y	AH26
4	IO_L181P_Y	AG25
4	IO_L181N_Y	AK27
4	IO_L182P	AM28[4]
4	IO_L182N	AF24[5]
4	IO_L183P_YY	AJ26
4	IO_L183N_YY	AP27
4	IO_VREF_L184P_YY	AK26
4	IO_L184N_YY	AN27
4	IO_L185P	AE23[4]
4	IO_L185N	AM27[5]
4	IO_L186P_Y	AL26
4	IO_L186N_Y	AP26
4	IO_VREF_L187P_Y	AN26[2]
4	IO_L187N_Y	AJ25
4	IO_L188P	AG24[4]
4	IO_L188N	AP25[5]
4	IO_L189P_YY	AF23
4	IO_L189N_YY	AM26
4	IO_VREF_L190P_YY	AJ24
4	IO_L190N_YY	AN25
4	IO_L191P_Y	AE22
4	IO_L191N_Y	AM25
4	IO_L192P_Y	AK24
4	IO_L192N_Y	AH23
4	IO_VREF_L193P_YY	AF22
4	IO_L193N_YY	AP24
4	IO_L194P_YY	AL24
4	IO_L194N_YY	AK23
4	IO_L195P_Y	AG22

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
4	IO_L195N_Y	AN23
4	IO_L196P_Y	AP23
4	IO_L196N_Y	AM23
4	IO_L197P_Y	AH22
4	IO_L197N_Y	AP22
4	IO_L198P_Y	AL23
4	IO_L198N_Y	AF21
4	IO_L199P_YY	AL22
4	IO_L199N_YY	AJ22
4	IO_VREF_L200P_YY	AK22
4	IO_L200N_YY	AM22
4	IO_L201P_YY	AG21[4]
4	IO_L201N_YY	AJ21[5]
4	IO_L202P_Y	AP21
4	IO_L202N_Y	AE20
4	IO_L203P_Y	AH21
4	IO_L203N_Y	AL21
4	IO_L204P	AN21[4]
4	IO_L204N	AF20[5]
4	IO_L205P_YY	AK21
4	IO_L205N_YY	AP20
4	IO_VREF_L206P_YY	AE19
4	IO_L206N_YY	AN20
4	IO_L207P_Y	AG20[4]
4	IO_L207N_Y	AL20[5]
4	IO_L208P_Y	AH20
4	IO_L208N_Y	AK20
4	IO_L209P_Y	AN19
4	IO_L209N_Y	AJ20
4	IO_L210P	AF19[4]
4	IO_L210N	AP19[5]
4	IO_L211P_YY	AM19
4	IO_L211N_YY	AH19
4	IO_VREF_L212P_YY	AJ19

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
6	IO_VREF_L265N_Y	AJ3
6	IO_L265P_Y	AG5
6	IO_L266N_YY	AD9[4]
6	IO_L266P_YY	AJ2[5]
6	IO_L267N_YY	AC10
6	IO_L267P_YY	AH2
6	IO_L268N_Y	AH3
6	IO_L268P_Y	AF5
6	IO_L269N_Y	AE8[4]
6	IO_L269P_Y	AG3[5]
6	IO_L270N_Y	AE7
6	IO_L270P_Y	AG2
6	IO_VREF_L271N_YY	AF6
6	IO_L271P_YY	AG1
6	IO_L272N_YY	AC9[4]
6	IO_L272P_YY	AG4[5]
6	IO_L273N_YY	AE6
6	IO_L273P_YY	AF3
6	IO_VREF_L274N_Y	AF1[2]
6	IO_L274P_Y	AF4
6	IO_L275N	AB10[4]
6	IO_L275P	AF2[5]
6	IO_L276N_Y	AC8
6	IO_L276P_Y	AE1
6	IO_VREF_L277N_YY	AD5
6	IO_L277P_YY	AE3
6	IO_L278N_YY	AC7
6	IO_L278P_YY	AD1
6	IO_L279N_Y	AD6
6	IO_L279P_Y	AD2
6	IO_VREF_L280N_YY	AB8
6	IO_L280P_YY	AC1
6	IO_L281N_YY	AC5
6	IO_L281P_YY	AC2

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
6	IO_L282N_Y	AA9
6	IO_L282P_Y	AC3
6	IO_L283N_Y	AC4
6	IO_L283P_Y	AD4
6	IO_L284N_Y	AA8
6	IO_L284P_Y	AB6
6	IO_L285N	AB1
6	IO_L285P	Y10
6	IO_L286N_Y	AB2
6	IO_L286P_Y	AA7
6	IO_VREF_L287N_Y	AA4
6	IO_L287P_Y	AA1
6	IO_L288N_YY	Y9[4]
6	IO_L288P_YY	AB4[5]
6	IO_L289N_YY	AA2
6	IO_L289P_YY	Y8
6	IO_L290N_Y	AA6
6	IO_L290P_Y	AA5
6	IO_L291N_Y	AB3[4]
6	IO_L291P_Y	Y7[5]
6	IO_L292N_Y	Y1
6	IO_L292P_Y	W10
6	IO_VREF_L293N_YY	Y5
6	IO_L293P_YY	Y2
6	IO_L294N_YY	W9[4]
6	IO_L294P_YY	W2[5]
6	IO_L295N_YY	W7
6	IO_L295P_YY	Y4
6	IO_L296N_Y	W1
6	IO_L296P_Y	Y6
6	IO_L297N_Y	W6[4]
6	IO_L297P_Y	W3[5]
6	IO_L298N_Y	V9
6	IO_L298P_Y	W4